

**Amendments to the Claims:**

1. **(Original)** A wafer support plate comprising:  
a support surface on which a semiconductor wafer is supported; and  
a crystal orientation mark which indicates a crystal orientation of the supported semiconductor wafer.
2. **(Original)** A wafer support plate according to claim 1, wherein said crystal orientation mark is formed at an outer-peripheral part of said support surface.
3. **(Original)** A wafer support plate according to claim 1, wherein said crystal orientation mark is formed on an outer-peripheral side surface of said support surface.
4. **(Original)** A wafer support plate according to claim 1, wherein said crystal orientation mark is formed by cutting away an outer-peripheral part of said support surface.
5. **(Currently amended)** A wafer support plate according to ~~any of claims 1 to 4~~ claim 1, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.
6. **(New)** A wafer support plate according to claim 2, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.
7. **(New)** A wafer support plate according to claim 3, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

8. **(New)** A wafer support plate according to claim 4, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.